

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-20. (canceled)

21. (previously presented) An NRD guide transition comprising:

a dielectric waveguide which is sandwiched between parallel conductors and has a gap which is less than a $1/2$ wavelength; a conductor rod which is adjacently arranged in substantially parallel with the dielectric waveguide; a microstrip line having a side surface opposite to the dielectric waveguide determined as a ground conductor with respect to the conductor rod; and

a coaxial line which pierces the conductor rod and a dielectric substrate of the microstrip line in a direction perpendicular to a longitudinal direction of the conductor rod and in parallel with the parallel conductors, and connects the dielectric waveguide with the microstrip line.

22-24. (canceled)

25. (previously presented) The NRD guide transition according to claim 21, wherein a lateral width of a contact surface of each of the conductor rod, the first conductor rod and the second conductor rod with respect to each of the parallel conductor plates is a $3/4$ wavelength, and a groove having a width

of a $1/4$ wavelength is provided at a central part of the contact surface in a longitudinal direction to form a choke structure.

26. (previously presented) The NRD guide transition according to claim 21, wherein a liquid dielectric material is filled in an air gap formed between contact surfaces of a dielectric substrate of the microstrip line and a cylindrical dielectric material constituting the coaxial line and an air gap formed between contact surfaces of the dielectric substrate of the microstrip line and the conductor rod.

27. (previously presented) The NRD guide transition according to claim 26, wherein the liquid dielectric material is a liquid dielectric material having dry curing properties.

28. (previously presented) The NRD guide transition according to claim 27, wherein the liquid dielectric material having dry curing properties is enamel.

29-39. (canceled)